

MVTX Status & Plan

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1st sPHENIX Workshop in China Peking University, Beijing, China



Outline

- Project Status
- MVTX full proposal
 - Physics and Simulations
 - Readout and Controls
 - Mechanical Integration
 - Budget and Schedule
- R&D Highlights
- Latest development



A Monolithic Active Pixel Sensor Detector for the sPHENIX Experiment

MVTX Status: Where do we stand?

- Full proposal submitted to BNL Associate Laboratory Director Dr. Berndt Mueller in Feb. 2018
- March 27, a meeting of ALD, MVTX principals, co-SP and sPHENIX project office. Given improved DOE funding fiscal outlook, ALD recommended to bring MVTX into MIE baseline:
 - This would be post-OPC/CD-1 Review(5/23-25, 2018), MIE baseline will be defined in the CD-2 (~summer 2019); MS Project -> P6 in progress
 - Exploring advance-funding options to procure Readout Units (\$250K, now) and staves from ALICE at CERN (\$1.2M, fall 2018)
 - Cost saving and reduce technical and schedule risks
 - ALD seeks DOE agreement to proceed
- MVTX workfest at MIT 4/30-5/1, 2018
 - Refine MVTX roadmap cost & schedule etc
 - Prepare for sPHENIX integration mini review (~summer)
 - MVTX+INTT+TPC...
 - Both electrical and mechanical systems

https://indico.bnl.gov/event/4380/

MVTX: Monolithic-Active-Pixel-Sensor-based VerTeX Detector



MVTX could also be a day-1 EIC detector

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Monolithic-Active-Pixel-Sensors (MAPS)

ALPIDE: The next Generation State of the Art Pixel Tracker

- Advantages of ALICE MAPS(ALPIDE): ٠
 - Very fine pitch (27x29 μm)
 - High efficiency (>99%) and low noise (<10⁻⁶)
 - Excellent time resolution, ~5 μs
 - Ultra-thin/low mass, 50μm (~0.3% X_n)
 - On-pixel digitization, low power dissipation

An ideal detector for sPHENIX and EIC physics!





A 9-chip MAPS stave, $9 \times (1.5 \times 3 \text{ cm}^2)$

Tower Jazz 0.18 µm CMOS

- feature size 180 nm
- metal layers 6 ٠
- gate oxide 3nm

substrate: N_A ~ 10¹⁸ epitaxial layer: N_A ~ 10¹³ deep p-well: N_A ~ 10¹⁶



sPHENIX Tracking System





MVTX Enables the 3rd Science Pillar

- 1. Jets
- 2. Upsilons
- 3. Open Heavy Flavor
- Bottom quarks are heavy (4.2 GeV)
- Produced in initial collision, probe QGP
 evolution
- Well controlled in pQCD
- Provide access to fundamental transport properties









MVTX Physics Highlights

- Heavy quarks unique probe of QGP w/ new scales, m_c, m_b
 - Study mass dependence
 - Jet quenching & energy loss
 - Flow interaction with medium
 - Access QGP properties
 - Temperature, density, coupling, transport coefficients, viscosity etc.

FHENIX Simulation R_{GP} (0-10%/60-80% (0-10% Au+Au vs...= 200 GeV Au+Au (5...-200 GeV, 240B ME PYTHIA-8 D-jet, Anti-k, R=0.4, jnl<0.7, CTEQ6 1.2 p+p; 200 pb⁻¹, 60% Eff., 40% Pur. -R-meson Å. 1LAT: 240B MB 40% Eff 40% Put - D⁰ from B D-meson 0.8 0.8 0.6 0.6 0.4 LANL D-bt R=0. 0.2 0.2 gmeg _ 2.0

Transverse Momentum [GeV/c]



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"B meson and b-jet flow"





"B meson and b-jet modification"

New Insight into QGP: HF-Jet Substructure



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New Insight into QGP: B v2

Very active theoretical investigation:

- LANL model
- CUJET

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- Duke model
- TAMU
- UrQMD
- AMPT
- PHSD
- Ads/CFT
- BAMPS
- HQ+EPOS2
- JetScape

Various new model calculations, PHSD, AMPT etc, for B-hadron v2:

- Significant non-zero v2 suggested, but may NOT follow the scaling due to large b-mass!

D-meson: v₂ scaling observed at RHIC









B-Hadron & b-Jet Tagging

- Detected using the long lifetime of bottom quark hadrons:
 - Displaced tracks
 - Large 2nd vertex invariant mass
- Need high precision tracking and vertex determination MVTX!
- Need excellent jet detection capabilities sPHENIX!





Simulation for *b*-jet and *B*-meson tagging





- Impact parameter (DCA) method to tag non-prompt D⁰ from B-meson decays
- Inclusive and exclusive channels possible

Partial reconstruction: B->D+x







b-jet Tagging in *p*+*p* and Au+Au

- Fully implemented MVTX models used in performance projection
- *b*-jet tagging projection evaluated with full tracking + calorimetry simulation
 - Tagging work point has been stable (60% Purity 40% eff for pp)
 - Central Au+Au Tagging work point has been stable (40% Purity 40% eff)
- Performance has been stable using truth jet finding or calorimetry reconstructed jet finding



MVTX Detector Integration

MVTX:



- Electrical system
 - Readout, power, controls
- Mechanical system
 - Support and cooling







MVTX Electronics, Power and Controls



MVTX Detector Electronics consists of three parts
Sensor-Stave (9 ALPIDE chips) | Front End-Readout Unit | Back End-FELIX

MVTX Full Readout Chain Demonstrated





Readout Unit + Stave

- Readout Unit configures Stave using USB interface
- FELIX distributes clock to Readout Unit
- Readout Unit distributes clock to the Stave
- Stave is triggered, sends data at 1.2Gb/s
- Configured GBT link to recover clock from FELIX
- Readout Unit receives the data and sends the data to FELIX over fiber using GBT link
- FELIX packs data, stores it on disk using RCDAQ the sPHENIX data formate and software



Server + FELIX



MVTX Test Beam at Fermilab: 02/20-03/10

- Goals:
 - Test full readout chain
 - Evaluate ALIPDE sensor performance
- Experimental setup
 - A 4-sensor telescope
 - Full readout chain: MAPS+RU+FELIX+RCDAQ

- Parasitic with INTT run
- Very productive & collaborative











Summary:

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- Successfully operated the full readout chain
- Confirmed all communications links and data path
- Confirmed telescope performance
 - Primarily 120GeV proton beam; also with low energy pion beams
 - Beam trigger rate ~7kHz
 - Tested High ALPIDE occupancy runs, with 10cm lead bricks in front of the sensors



Fermilab Test Beam Results (I)



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Fermilab Test Beam Results (II)



4/22/18



ALPIDE Readout Optimization and Trigger Latency Study

- Expected sPHENIX trigger latency 4~5 uS
- Two possible readout modes: 1) Triggered and 2)Continuous



- OUT_A clipping: VCLIP. Decreasing VCLIP decreases clipping point.
- OUT_A returns to baseline time: ITHR, VCLIP. Increasing ITHR decreases discharge time, and decreasing VCLIP decreases discharge time after clipping.
- OUT_D return to baseline time: IDB. Increasing IDB increasing charging time hence decreasing pulse duration.



A Test Bench at LANL



ALPIDE chips.

Power Board



Trigger Latency and Signal Shaping Time Study

• Lower the OUT_D threshold (IDB) increases the trigger duration time, but also increases the cluster size which might include more background hits.

In the continuous readout mode, "trigger/strobe" can be as early as ~1uS





Model of MVTX with INTT inside TPC with the addition of two concentric composite cylinders;



Location in Z where the inner-hcal ends (see control drawing) Z=2175.0 mm



MVTX and INTT Integration – Work in Progress



It is clear from this detail view the conical region of the MVTX detector barrel with the INTT that the MVTX will need to translate in Z...



Signal and Power Extension for FPC

IB Services: cabling&cooling







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MVTX Mechanical Conceptual Design

 View of MVTX half detector assembly with extended central barrel







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sPHENIX MVTX Cost & Schedule Profile



New numbers: \$1.52M \$1.6M

RU units moved from FY19 to FY18

* 50% cost reduction due to joint production with ALICE

FY20-22: funding profile smoothing



Updated Major Cost Items

WBS	Task Name	Cost (K)	Cost with Contingency+ Passthru (K)
1.5.3.1.1	Produce 84 staves	\$966	\$1.2M \$1337
1.5.2.2	Readout Units(RDO)	\$480	\$250K \$664
1.5.5.3.2.3.2	CYSS Cylindical Structure	\$319	\$424
1.5.5.3.2.3.3	COSS Conical Half Shell	\$329	\$438
1.5.4.3	Safety Systems	\$139	\$191
1.5.4.4	Stave Support+ Global Interface	\$308	\$465

Table 6: Major Cost Items



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Summary and Outlook

- MVTX full proposal completed
 - Expanded science
 - sPHENIX baseline
- Cost and schedule update in progress
 - Major item cost
 - Funding profile smoothing
- Excellent progress in R&D
 - Readout and controls proof-of-principle demonstrated
 - Conceptual mechanical system design being developed
- MVTX+INTT+TPC integration in progress
 - Electrical and mechanical system
 - sPHENIX wide coordination through Office of Integration
- To be ready for sPHENIX Day-1 Physics in 2023
 - sPHENIX and later EIC possibility

Welcome Contributions from Chinese Consortium!

Document: sPH-HF-2018-001 https://indico.bnl.gov/event/4072/



Backup slides

Physics & Simulations: from sPHENIX to EIC





RHIC Multi-Year Plan: sPHENIX 2023-2027+



Year	Species	Energy [GeV]	Phys. Wks	Rec. Lum.	Samp. Lum.	Samp. Lum. All-Z
Year-1	Au+Au	200	16.0	$7 \ { m nb^{-1}}$	$8.7~{ m nb^{-1}}$	$34 \ \mathrm{nb^{-1}}$
Year-2	p+p	200	11.5		$48~{ m pb}^{-1}$	$267~{ m pb^{-1}}$
Year-2	p+Au	200	11.5		$0.33 { m ~pb^{-1}}$	$1.46 { m ~pb^{-1}}$
Year-3	Au+Au	200	23.5	14 nb^{-1}	$26~{ m nb^{-1}}$	$88 \ \mathrm{nb^{-1}}$
Year-4	p+p	200	23.5		$149~{ m pb}^{-1}$	$783~{ m pb}^{-1}$
Year-5	Au+Au	200	23.5	14 nb^{-1}	48 nb^{-1}	$92~{ m nb^{-1}}$

- Precision B-tagging w/ MVTX:
 - Tracking resolution better than 50um @pT=1GeV
 - High multiplicity HI collisions
 - Low multiplicity but high rate p+p collisions
 - High efficiency and high purity




Summary: Major Remaining R&D

- Mechanical/Electrical integration with INTT+TPC
 - Carbon structure design
 - FPC extension
- Full electrical system control
 - Power
 - Safety
 - Online monitoring & controls
- Readout system firmware/software with slow controls



More information

Mechanical Integration

sPHENIX Integration: MVTX + INTT + TPC





INTT-MVTX Conflict **INTT** Acceptance @ |z|=10 |η|<0.95 **INTT 4-layers** |η|<1.09 |η|<1.28 |η|<1.12

- Currently a clear conflict between the INTT and MVTX
 - INTT only includes ladder, no connectors, cooling barbs, etc

R&D items: 1) Extend cables to move the conical structure further out in zdirection; 2) Design/optimize INTT layers to fit current MVTX geometry;

- FPC data cable is the HDI and can't be easily extended, short "firefly" cables possible?
- Reduce angle of cone redesign C-structures and connectors

INTT-MVTX Conflict



- Possibly add short "firefly" cables to hook up to patch panel, R&D needed
- 2. Reduce angle of cone redesign



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MVTX/INTT Integration Extend MVTX Service Cables?



The 9 silicon chips are read out in parallel: each chip sends its data stream to the end of Stave by a dedicated differential pair, 100 μ m wide. Two additional differential pairs distribute the clock and configuration signals.

MVTX FPC R&D @CERN and LANL













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MVTX half detector assembly

MVTX Detectors



Service Barrel: Design and Fabrication



ALICE HALF-BARREL ASSY

ALICE Inner Tracker Rail Support

The MVTX plus INTT half barrel assemblies location position is provided by the engagement of 4 rollers on the half-barrel, which would be previously measured and aligned, into four precise inserts housed in the "cage-rail" assembly.



In sPHENIX we will not use a "service cone, rail system" anywhere near the size of that planned for the ALICE detector, but we will use their concept.

INTT Readouts from both North and South



Minimum length is 105cm – ladder length + distance to ROC board.

BNL control envelope drawing; Z location of the inner hcal is at 2175,0mm



Cross-section view from CAD model of MVTX, INTT, TPC, beam-pipe, plus two composite conical shells



Gap between conical shell of MVTX and inner layer of INTT is 11.58 mm





56.0 mm gap between INTT and inner radius of TPC





Earlier model for the INTT, chevron configuration, inner layer half ladders in width;



Offset from OD of beampipe and innermost component of the MVTX



Offset needed to install split MVTX into run location around beampipe, passing over 2.75 in conflat flange



INTT stave design with HDI



Latest configuration of ladders in the INTT, 4 layers where each is made from two layers for hermeticity



New INTT model with HDI extensions;



Cost & Schedule

Cost and Schedule I the Full Propsal

- Total budget: 6.5M
 - Production
 - Assembly

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- Integration
- About 9 months schedule float



sPHENIX MVTX Cost Profile

Figure 42: MVTX Funding Profile.

Major Items	Cost (\$M)	Schedule
Staves (WBS 1.5.3.1)	1.3	8/2018-5/2019
Readout & Controls (WBS 1.5.2)	1.3	1/2019-6/2019
Mechanics & Detector Assembly (WBS 1.5.3)	1.8	2019-2022, TBO
Integration (WBS 1.5.4)	1.0	2021-2022, TBO
Project Management	1.0	8/2018-1/2023



MVTX labor profile in the full proposal

12000

10000

8000

6000

4000

2000

0

FY2019

	Escalation + Overhead + Contingency	
Labor	\$2.5M	
M&S	\$4M (\$3.75M if RU produced in FY18)	



Resource by Hours

Only engineers and Technical staff costed to the project

FY2021

PHYS ENG Tech GRDSTD

FY2022

FY2020

FY2023

Early funding motivation for MVTX FY18,FY19

- Buy 84 good staves from CERN following ALICE production, end FY18
 - Includes: sensors, space frame, FPC, assembly and tests
 - Very low technical risk
 - CERN will deliver 100% working staves
- Buy 58 Readout Units with the ALICE production in FY18 (was FY19)
 - FPGA chips and GBT chips as part of the ALICE production
 - GBT not commercially available product
 - ~50% cost saving w.r.t. to estimated budget (exact number confirmed 04/18)
- MVTX telescope Fermilab test beam confirmed the readout chain and sensor performance in early March 2018
 - Sensors(ALPIDE) + RU(frontend) + FELIX(backend) + sPHENIX RCDAQ
- To attract external funding & support for MVTX
 - Foreign consortium, individual institution

M&S cost options & risks

Green: low risk / MVTX baseline budget Red: High technical risk, low cost saving or increased cost

• Staves:

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- Oprion1: MVTX production following ALICE production at CERN, ~Aug 2018
 - All material included and 100% working staves delivered
- Option2: Partial stave assembly at CCNU (China)
 - MVTX project would still need to buy sensors, Flexible Printed Circuit (FPC) and space frames
 - Wuhan could assembly sensor and FPC; assembly with space frame may be done elsewhere
 - No experience assembly inner barrel \rightarrow training required and hardware modified
 - Potential saving on some labor assembly work
 - Yield unknown -> schedule and cost uncertainty
- Readout Units (radiation hard electronics):
 - Option1: Produce with ALICE batch (FPGA chips & GBT chips) in FY18
 - 50% cost reduction w.r.t. budgeted cost
 - Option2: MVTX produces its own batches → cost increase and schedule impact
- Carbon structures:
 - Exploring cost-saving options, build carbon structures elsewhere (France and Italy) instead of LBNL etc.
- Reuse hardware from LDRD
 - Electronics, Power System etc.

LANL LDRD – MVTX/sPHENIX Key Tasks/Milestones



Electronics and Controls

MVTX Electronics Overview



MVTX Detector Electronics consists of three parts
Sensor-Stave (9 ALPIDE chips) | Front End-Readout Unit | Back End-FELIX

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Sensor and Electronics R&D @LANL

- ALPIDE evaluation and optimization
 - MOSAIC + Single Chip/Stave
 - Cosmic and source
 - Laser system
- Power unit tested
 - PU + MOSAIC
 - PU + RU
- Full readout chain demonstrated
 - ALPIDE + RUv1.0 + FELIX v1.5 + RCDAQ
 - Full stave + RUv1.x + FELIX v2.0 + RCDAQ
- Mechanical system integration
 - Conceptual design developed
 - MVTX+INTT integration





First Full Chain Readout: Success!

LANL + Martin, JohnH et al



- RU configures ALPIDE using python scripts interfacing the USB chip on RU
- Felix distributes clock to RU, the RU then distributes the clock to the ALPIDE
- ALPIDE is triggered on the control line, sends data at 1.2Ghz over copper
- The RU receives the data and sends the data to FELIX over fiber using GBT link
- FELIX packs the data and stores in on disk which is read out using RCDAQ
- Configured ALPIDE to accept triggers from FELIX using python software that came with the RU
- Configured GBT link to recover clock from FELIX and GT link (FGPA gigabit interface)
- 8 RU's emulated using 1 fiber link per RU on FELIX, 15kHz, 400 hits per RU
- Currently working the implementation of the above using a Stave

RUv1.0


Parallel Effort at UT-Austin – Shared R&D

Test Setup at UT Austin

ALICE ITS UPGRADE

- RUv1 with transition bd + power mezz
- RUv0 as CRU emulator
- Single sensor on chip carrier board with interface board (only usable for IB tests, wrong pins for OB)

- Long (5m) FireFly cables
- Power board with single breakout board
- Now also tested with 9-sensor Inner Barrel module





LANL R&D: Single ALPIDE Chip Scan – Active Channel Fraction

- Scanned the available chips and stave at the LANL lab through digital scan to verify the dead channel fraction: the bad channel fraction is <1%.
- Similar results with different readout speeds.





Hit Pixel Cluster Distribution from Source Test (Sr⁹⁰)



Achieved all goals and more!

- Tested a new readout scheme
 - 4 sensors (~4 staves) per RU (ALICE 1 stave per RU)
- Sensor performance evaluation
 - Cluster size

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- Threshold, signal shaping, trigger delay
- System stress test
 - High multiplicity events created via lead bricks "shower"
 - With 5, 10, 20cm lead bricks
- Analysis software developed
 - Online monitor
 - hit distribution, relative alignment etc.
 - Offline reconstruction, alignment etc.
 - Preliminary alignment, ~O(100um)



4 sensors Connectec to one RU





RC DAQ event Data Screen Shot

- Rcdaq receiving events from KC705 using ddump utility
- ffff0044ffffc0ff4ea0
- a0 Chip Header
- 4e bunch counter
- ff IDLE
- c0 Region Header
- 40 00 first Hit
- Second screen shot showing end of one event (b0..., f000f000) and the beginning of another

					maps : ddump - Konsole						maps:ddump -	Konsole		×
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90	60ff0156	c 160ff00	6401ff	ff0164ff		68	48ff0144	148ff00	4c01ff	ff014cff				1
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d4	10174f	f ff0078ff	7cff0178	510100		ac	1015cff	fccsoff	64ff0160	420100				1
d8	101/4f	f 40ffffc7 f ffoodaff	40110100 Actf0148	441101		60	ff0164ff (58 ff 0068	5cff0101	16cff00				
eO	ff014cf1	f Soffooso	54ff0101	154ff00		54 b8	ff0078ff :	7cff0178	7cff0100	450101 ffc6ff01				
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68 80	101601	f ff006cff	54110100 70ff016c	5ett01			ff0048ff 4	Actf0148	4cff0100	50ff01				1
fo	ff0170f	f 74ff0074	78ff0101	178ff00		c4 c8	ff0158ff	Scff005c	58110154 60ff0101	160ff00				1
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	1015cf	f ffoosoff	64ff0160			dc	10144ff	fco48ff	4cff0148	540100				II.



Data Rate Calculations

	Collision Rate
Au Au	200kHz
PP	10Mhz

• Assume 10us window and cluster size 3

	Au Au	P P
# of collisions	2 = 10us * 200kHz	100 = 10us * 10Mhz
# of hits, hottest chip	270 = 3 * 90	75 = 3 * 25
# of hits in a stave	1983 = 3 * 661	543 = 3 * 181

Central Au-Au collision with 2.0 pileup MB collisions: 661 clusters/stave in layer 0



30 20 10

oE

-15

-10

-5

0

5

10

Expected Data Rate (from the proposal)



Figure 9: Average hit occupancy per event. Conservative assumptions are made regarding integration time $(10 \,\mu s)$ and cluster size (3 pixels/cluster). In addition, the pileup collisions are assumed to occur inside the MVTX acceptance ($|Z_{Venex}| < 10 \text{ cm}$) when in fact they will be widely distributed along the beam axis.

The highest occupancies are expected in layer 0, at $\eta = 0$, with central Au+Au collisions. Figure 9 shows that MVTX sensors average 271 hit pixels/event, for an occupancy of 0.052%. Lab tests (further described in Section A) have demonstrated successful MVTX readout at larger hit occupancies.

	10 ⁻⁴ noise	Hit occupancy only		Hit + noise occupancy		
	occupancy	<i>p</i> + <i>p</i> [MB/s]	Au+Au [MB/s]	<i>p</i> + <i>p</i> [MB/s]	Au+Au [MB/s]	
L0 FEM	26	29	107	55	133	
DAM	219	173	630	392	848	
MVTX	1305	1041	3781	2346	5089	

Table 2: Raw (uncompressed) data rates based on a worst-case noise occupancy of 10^{-4} , the hit occupancies of Fig. 9 at 15 kHz trigger rates, and the sum of the hit and noise.

Physics & Simulations: from sPHENIX to EIC







sPHENIX Projected R_{AA} Sensitivity

Open questions to be answered: energy loss mechanisms and QGP medium properties



sPHENIX Project Elliptical Flow v₂

Open questions to be answered: nature of quasi-particles, medium interactions and transportation





New calculations from PHSD for B-hadrons:

- Potential significant anti-shadowing effects
- Open b-bar in AuAu, very important baseline for Upsilon program!



Project Organization



Figure 40: Organization chart of the MVTX project.